

FXT01-XXXX-X Mounting Instructions



Socket Hardware:

- 1) Socket hardware is supplied with every shipment. *PariPoser® Contactor*
- 2) Sockets and mounting hardware are packaged separately.

Before Board Assembly:

- 1) Every caution should be taken not to touch or pierce the *PariPoser® Contactor*. The socket should not be exposed long before mounting on the test board.
- 2) Socket assembly to the test board should be performed in a clean environment.

At the Board Assembly:

- 1) First air blast the board pads using canned air cans then mount the socket on the test board using two fine alignment pins matching the Pin-1 corner on socket (Molded Pin-1 indicator on Lid) and the board.
- 2) Place Backer plate (with Insulation tape pre-assembled on top) on the bottom side of the test board orienting in a way that Backer plate's chamfer corner goes under the pin-1 corner of the socket.
- 3) Install spring lock washer and then nuts on the screws.
- 4) Tighten the nuts to a torque of 40-50 oz-in using a properly calibrated tool, in correct order (1-4) as shown below.

Note: Once the lock washer is flattened, any additional tightening Serves No purpose.

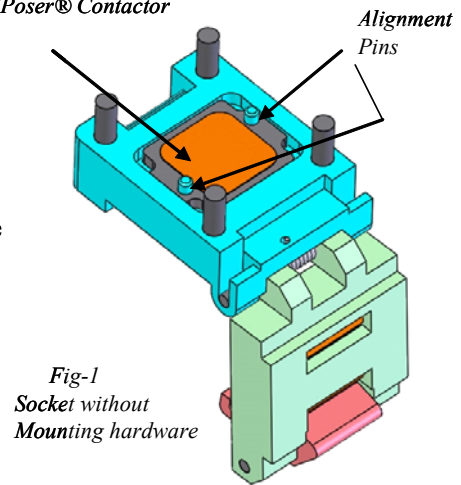
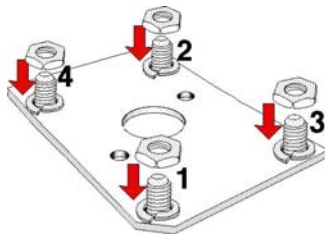
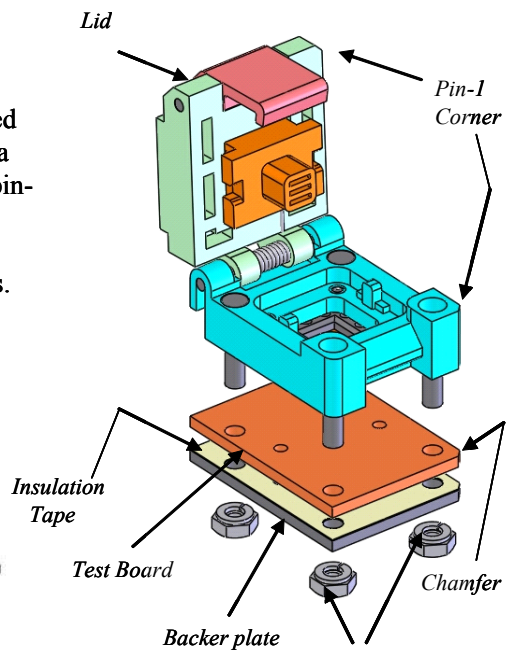


Fig-1
Socket without
Mounting hardware



Lock Washers &
Mounting Nuts

Fig-2

Note:

The above mentioned mounting instructions need to be followed for proper performance of the socket. When these mounting instructions are not followed, the user is solely responsible for the socket performance.

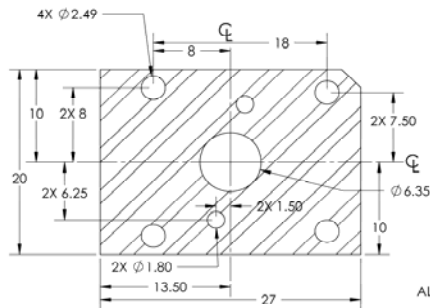
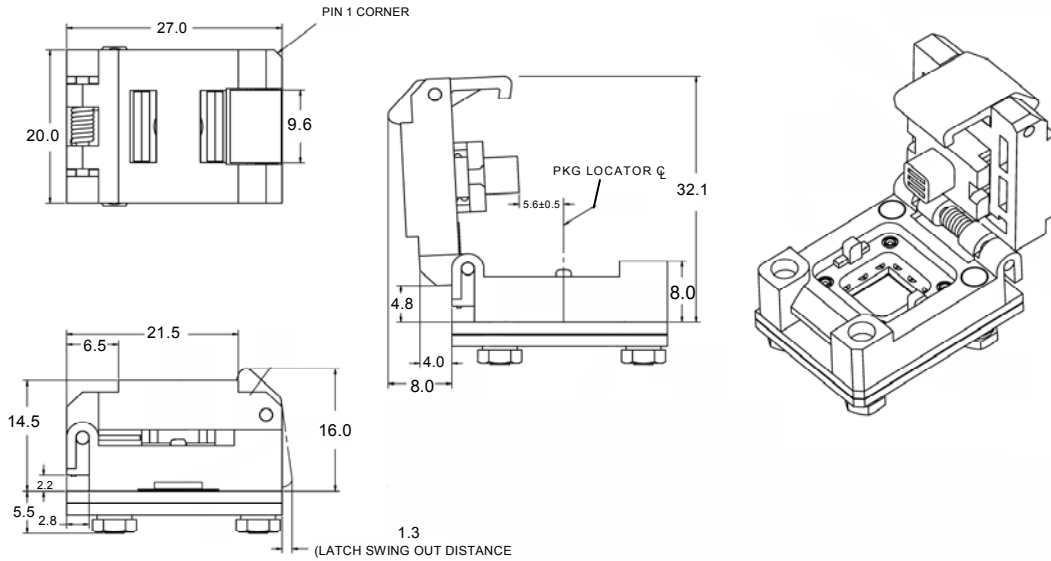
Board Layout – CSP/QFN Type Test Sockets

(3x3) - FXT01-XXXX-3

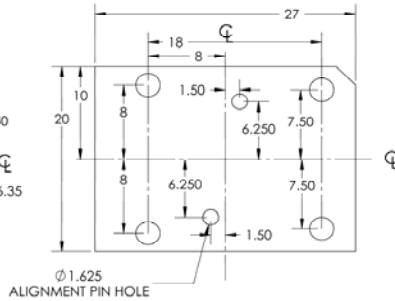
(5x5) - FXT01-XXXX-5

(4x4) - FXT01-XXXX-4

(6x6) - FXT01-XXXX-6



STIFFENER PLATE
BACK SIDE OF PCB
KEEP OUT ZONE



RECOMMENDED PCB FOOTPRINT
ϕ REFERS TO CENTERLINE OF
PAD ARRAY

PCB CONSTRUCTION INSTRUCTIONS

1. NO SURFACE TRACES ALLOWED ON THE PCB TOP SURFACE BETWEEN THE PADS & PAD MATRIX AREA.
2. NO SOLDER MASK ON BOARD UNDER CONTACTOR
3. SOLID PADS, NO DOG BONES
4. FILLED VIAS RECOMMENDED
5. OPTIMUM PAD CONSTRUCTION
 - 30 MICRO-INCH HARD GOLD
 - 50 MICRO-INCH NICKEL
 - >1 OZ COPPER

See Application Guidelines for full board construction details

Rev 2-07

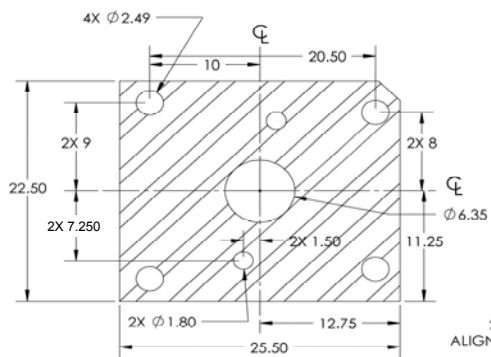
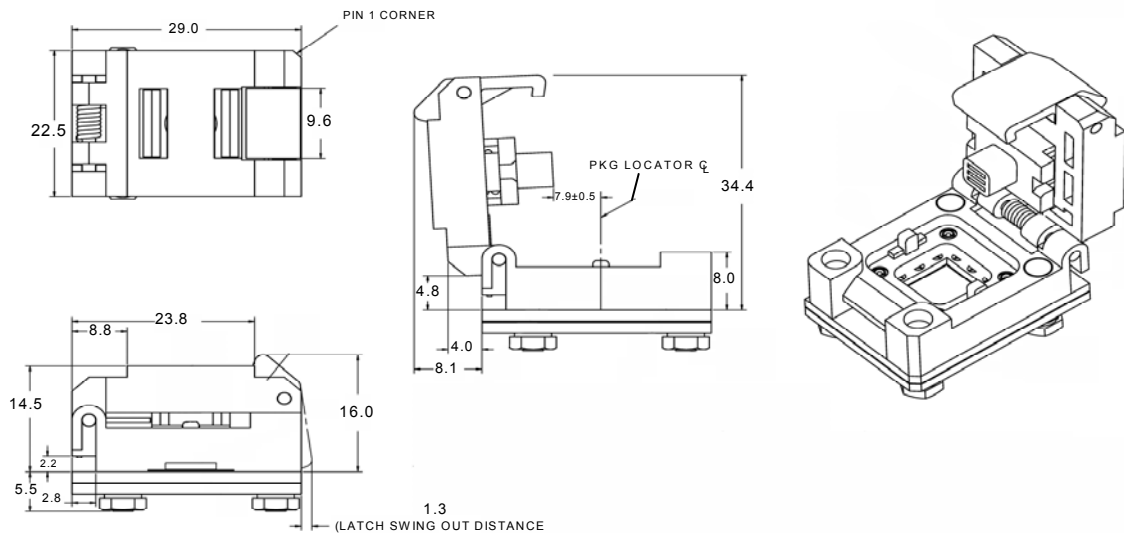


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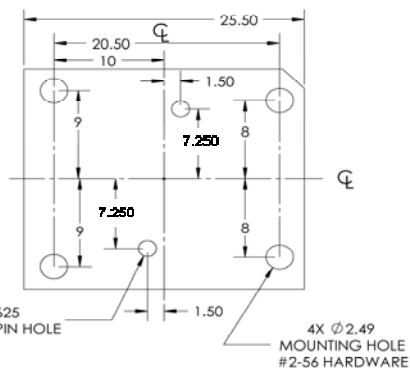
Board Layout – CSP/QFN Type Test Sockets

(7x7) - FXT01-XXXX-7

(8x8) - FXT01-XXXX-8



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BACK SIDE OF PCB
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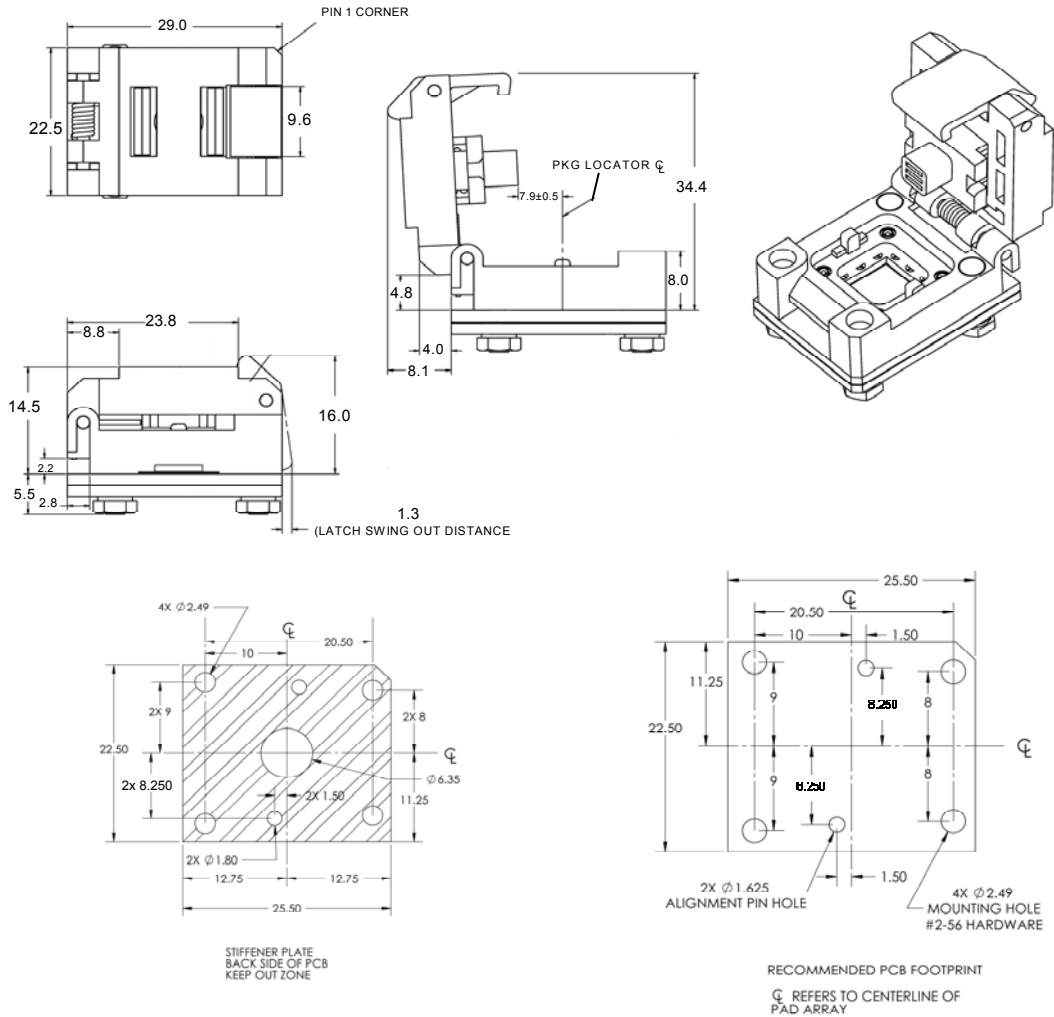


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Board Layout – CSP/QFN Type Test Sockets

(9x9) - FXT01-XXXX-9

(10x10) - FXT01-XXXX-10



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